## **AN7174K-LC**

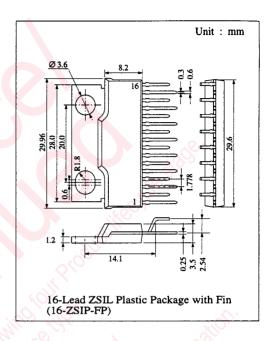
## Dual BTL 14W Audio Power Amplifier

### Description

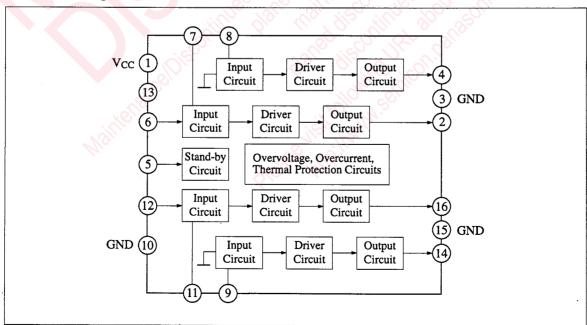
The AN7174K-LC is a monolithic integrated circuits designed for 14W (13.2V,  $4\Omega)$  output power amplifier. Stereo operation is enabled due to incorporating two BTL amplifiers in one chip. High reliability is obtained due to incorporating various protectors. ON/OFF is enabled even if power is supplied to power supply pin by incorporating stand-by circuit.

#### ■ Features

- High output power (BTL 14W x 2)
- Incorporating stand-by circuits
- Incorporating protection circuits. (Temperature, overvoltage, V<sub>OUT</sub>-GND short, Load short, V<sub>OUT</sub>-V<sub>CC</sub> short)
- Low shock noise from power ON/OFF operation
- Fewer external components
- Highly stable operation



## Block Diagram



### ■ Absolute Maximum Ratings (Ta=25°C)

Item	Symbol	Rating	Unit
Supply Voltage	V <sub>CC</sub> *1	24	V
Supply Current	I <sub>CC</sub>	6	A
Supply Voltage Surge	V <sub>CC(surge)</sub> *2	50	V
Power Dissipation	P <sub>D</sub> *3	62.5	W
Operating Ambient Temperature	Topr	-30 ~ +75	°C
Storage Temperature	Tstg	-55 ~ +150	°C

Operating Supply Voltage Range:  $V_{CC} = 8.0V \sim 18.0V$ 

## ■ Electrical Characteristics (V<sub>CC</sub>=13.2V, R<sub>L</sub>=4Ω, f=1kHz, Ta=25°C)

Item	Symbol	Condition	min.	typ.	max.	Unit
Quiescent Current	I <sub>CQ</sub>	$V_{in} = 0mV$	.00	120	200	mA
Output Noise Voltage	V <sub>no</sub> *	$V_{in} = 0$ mV, $R_g = 10$ k $\Omega$	HILL	0.6	1.5	mV
Voltage Gain	Gv	$V_{in} = 5mV$	50.5	52.5	54.5	dB
Total Harmonic Distortion	THD	$V_{in} = 5mV$		0.2	0.75	%
Maximum Output Power	Po	THD = 10%	9.0	12.5		w
Ripple Rejection	RR*	$R_g = 0\Omega, V_{in} = 0 \text{mV}, V_r = 300 \text{mV},$ $f_r = 120 \text{Hz}$		40	×	dB
Output Offset Voltage	V <sub>O(offset)</sub>	V <sub>in</sub> = 0mV	-200	0	+200	mV
Channel Balance	СВ	$V_{in} = 5 \text{mV}$	<del>\\\-1</del>	0	O <sub>+1</sub>	dB
Total Harmonic Distortion	THD	$V_{in} = 5mV, f = 100Hz$	-01	0.26	101	%
Total Harmonic Distortion	THD	$V_{in} = 5mV$ , $f = 10kHz$	16	0.45	0.2	%
Frequency Characteristics	f <sub>CH</sub>	$V_{in} = 5 \text{mV}, -3 \text{dB down}$		22		kHz
Frequency Characteristics	f <sub>CL</sub>	$V_{in} = 5mV$ , -3dB down		21		Hz
Quiescent Circuit Current at Stand-by Pin ON	I <sub>CQ(STBY-ON)</sub>	Stand-by Pin ON	1.691	21		μА
Crosstalk	CT	$V_{in} = 5 \text{mV}, R_g = 10 \text{k}\Omega$	<b>P</b>	61		dB

<sup>\*</sup> With 15Hz ~ 30kHz (12dB/OCT) filter

### ■ Pin

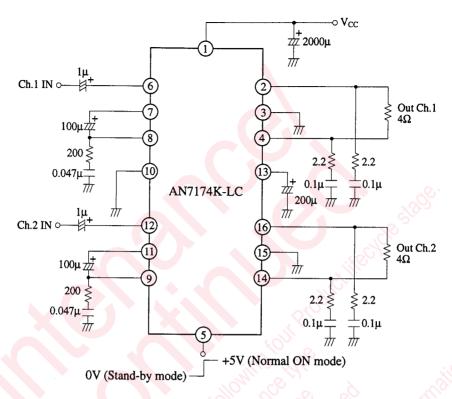
Pin No	Pin Name	. 00	Pin No	Pin Name
1	V <sub>CC</sub>	6/0	9	N.F.B. Ch.2
2	Output Ch.1		10	GND (Input)
3	GND (Output Ch.1)		11	N.F.B. Ch.2
4	Output Ch.1		12	Input Ch.2
5	Stand-by		13	Ripple Filter
6	Input Ch.1		14	Output Ch.2
7	N.F.B. Ch.1		15	GND (Output Ch.2)
8	N.F.B. Ch.1		16	Output Ch.2

<sup>\*1</sup> No-signal

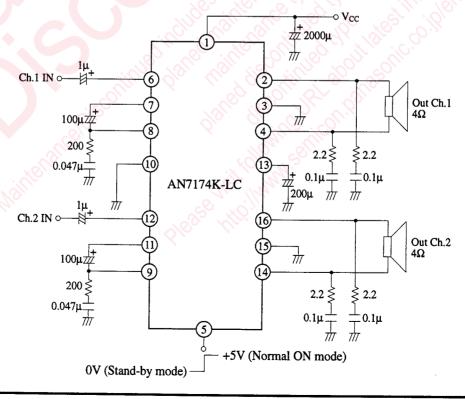
<sup>\*2</sup> Time = 0.2s

<sup>\*3</sup>  $R\theta_{j-c} = 2^{\circ}C/W$ 

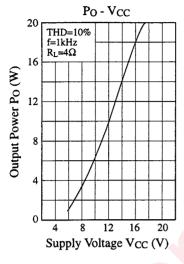
### **Test Circuit**

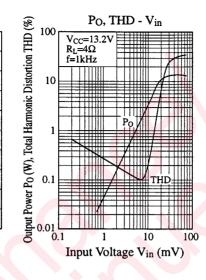


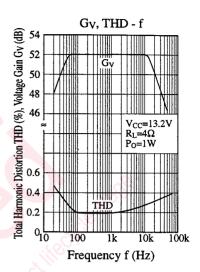
## Application Circuit

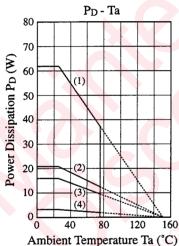


#### ■ Characteristics Curve









- (1)  $Tc=Ta,62.5W (\theta_{i-c}=2^{\circ}C/W)$
- (2) 20.8W (θ<sub>f</sub>=4°C/W) With a 100cm<sup>2</sup> x 3mm Al heat sink (black colour coated) or a 200cm<sup>2</sup> x 2mm Al heat sink (not lacquered)
- (3) 15.6W (θ<sub>f</sub>=6°C/W) With a 100cm<sup>2</sup> x 2mm Al heat sink (not lacquered)
- (4) 3.0W at Ta=30°C Without heat sink

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